



JAE Electronics, Inc.  
April 2<sup>nd</sup>, 2023

## ENG-E23-034 - Distributors

### PCN (Process Change Notice) MX34016SF1 Replacement mold die (1J,1K,1L,1M,1N,1P,1Q,1R) To Keep Production Capacity

Part Number	Existing Mold Dies	1 Replacement Mold Die created with 8 cavities	Replacement Mold Die Completion	Proposed PPAP Submission	Start of Mass Production (SOP)
MX34016SF1	(T,U,V,W),(HA,HB,HC,HD), (HE,HF,HG,HH),(HJ,HK,HL,HM), & (HN,HP,HQ,HR,HS,HT,HU,HV) *Pending PCN, ENG-E22-017 Replacement mold die (1A,1B,1C,1D,1E,1F,1G,1H) will be created to replace (T,U,V,W) & (HA,HB,HC,HD), released on 2/27/22	(1J,1K,1L,1M,1N,1P,1Q,1R) to replace die (HN,HP,HQ,HR,HS,HT,HU,HV)	September 2023	November 2023	February 2024

#### Notes:

- PC = Process Change (Tooling: Transfer, Replacement, Refurbishment, or additional and Parts Produced at Additional Location, etc...)
- PPAP = Production Part Approval Process
  1. PC PPAP will only be prepared and provided to customer who already requested and received initial PPAP.
  2. If you request PC PPAP documents for this notification, please notify us ASAP.